



100% Material Declaration Data Sheet CSG280

PK204 (v1.0) October 5, 2006

Material Declaration Data Sheet

Average Weight: 0.6180 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0253	4.10%
	Silicon	7440-21-3	100.00		0.0253	
Die Attach Material					0.0033	0.53%
	Resin	Trade Secret	22.00		0.0007	
	Silver	7440-22-4	78.00		0.0025	
Mold Compound					0.2890	46.76%
	Resin	Trade Secret	12.00		0.0347	
	Silica	60676-86-0	88.00		0.2543	
Laminate					0.1770	28.65%
	Copper	7440-50-8	16.72	Metal Layer	0.0296	
	Nickel	7440-02-0	4.41	Metal Layer	0.0078	
	Gold	7440-57-5	0.79	Metal Layer	0.0014	
	Board	Trade Secret	63.62		0.1126	
	Solder Mask (EP)	Trade Secret	14.46		0.0256	
Gold Wire					0.0108	1.74%
	Gold	7440-57-5	100.00		0.0108	
Solder Balls					0.1126	18.22%
	Tin	7440-31-5	95.50		0.1076	
	Silver	7440-22-4	4.00		0.0045	
	Copper	7440-50-8	0.50		0.0006	

PK204 (v1.0) October 5, 2006

www.xilinx.com

1

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.